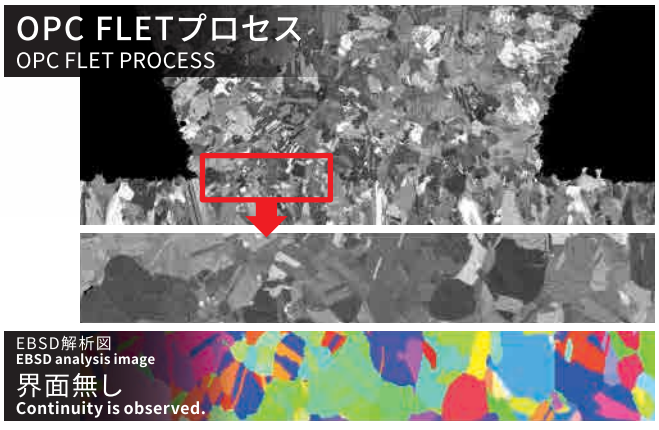
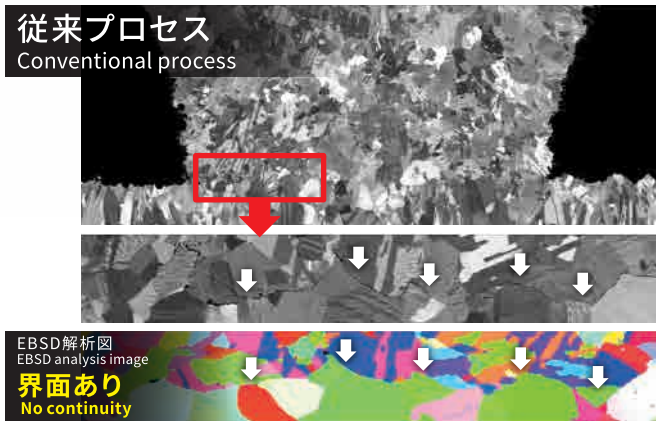
接続信頼性に優れる無電解銅めっきプロセス
Electroless Copper Plating Process for Higher Connecting Reliability

OPC FLETプロセス
OPC FLET PROCESS

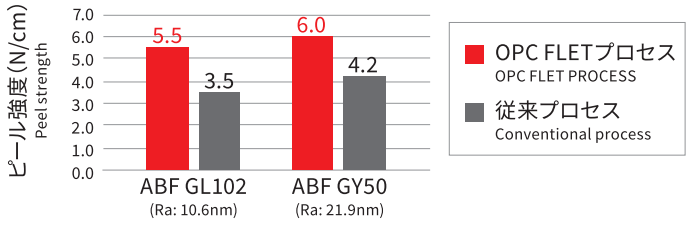
- ビア底の結晶連続性が得られ、接続信頼性に優れる
  Can obtain crystal continuity at via-hole bottom, excellent in connecting reliability
- 低粗度材料でも高いピール強度が得られる
  High peel strength to low Ra material
- 低膜厚で低いシート抵抗値を示し、通電不良なく硫酸銅めっきが可能である
  Low sheet resistance value by thin thickness, can make acid copper plating without causing conduction failure
- 低膜厚で優れたビア・スルーホール内のめっき析出性が得られる
  Can realize high via-, through-hole plating ability by thin thickness

優れた結晶連続性 Excellent in crystal continuity

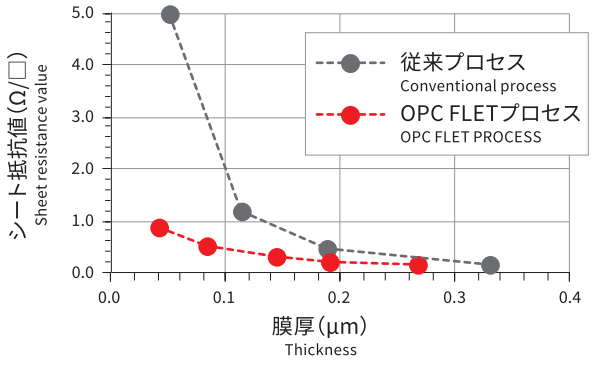




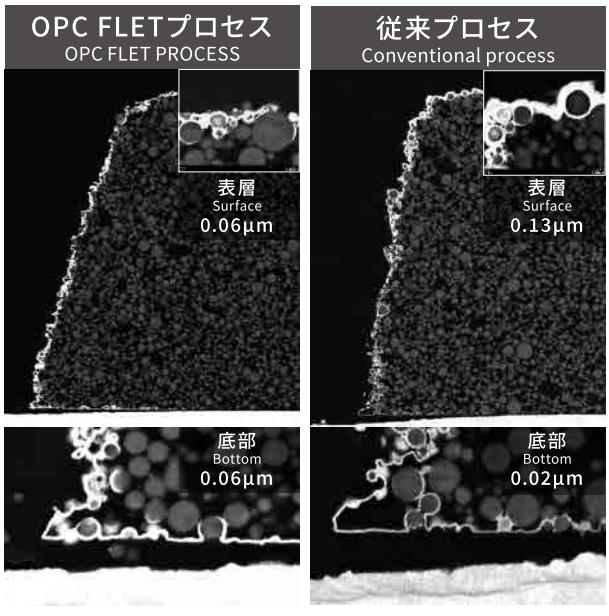
低粗度材料でも高いピール強度
High peel strength to low Ra material



低膜厚でも低いシート抵抗値
Low sheet resistance can be realized by thin thickness



低膜厚で優れたビア付きまわり性
Great covering power by thin thickness into via holes



100%　15%

スローイングパワー
Throwing power